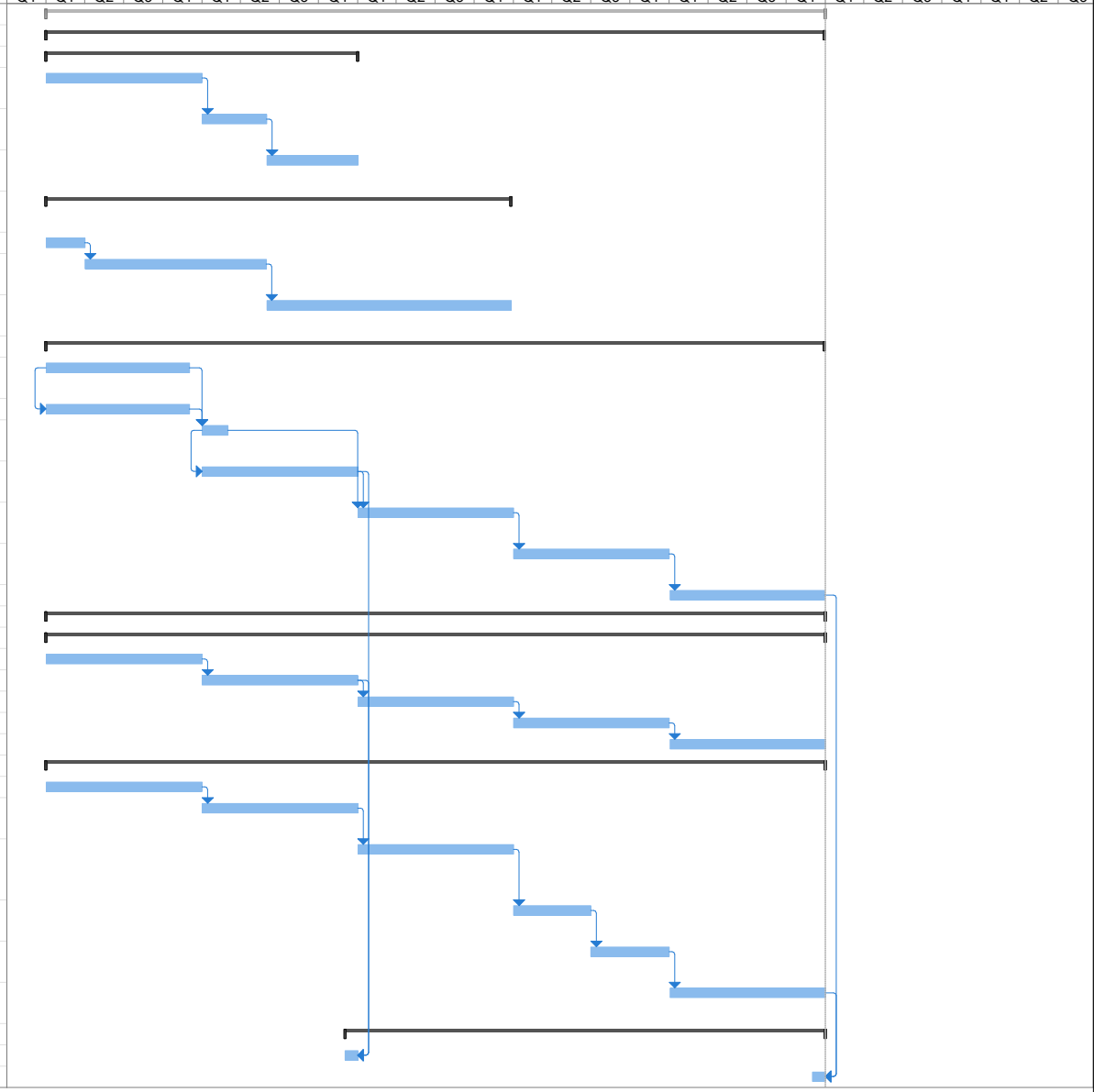ID	Task Name	Text1	Duration	Start	Finish
0	**硅径迹探测器**	**Silicon track detector**	**1305 days**	**2024/1/1**	**2028/12/31**
1	**1）硅微条探测器**	**1) Silicon micro strip detector**	**1305 days**	**2024/1/1**	**2028/12/29**
2	**1.1）传感器与读出芯片**	**1.1) sensor and readout chip**	**523 days**	**2024/1/1**	**2025/12/31**
3	1.1.1）传感器与读出芯片关键性能测试	1.1.1) key performance test of sensor and readout chip	262 days	2024/1/1	2024/12/31
4	1.1.2）传感器、芯片在不同辐照条件下的性能表现	1.1.2) performance of sensors and chips under different irradiation conditions	108 days	2025/1/1	2025/5/31
5	1.1.3）参与批量生产阶段可靠性测试	1.1.3) participate in reliability test in batch production stage	153 days	2025/6/2	2025/12/31
6	**1.2）硅微条探测器研制**	**1.2) development of silicon micro strip detector**	**780 days**	**2024/1/1**	**2026/12/25**
7	1.2.1) 模块站点考核	1.2.1) module site assessment	65 days	2024/1/1	2024/3/31
8	1.2.2) 制备长硅微条模块	1.2.2) preparation of long silicon micro strip module	305 days	2024/4/1	2025/5/30
9	1.2.3) 制备短硅微条模块	1.2.3) preparation of short silicon micro strip module	410 days	2025/6/2	2026/12/25
10	**1.3）系统集成**	**1.3) system integration**	**1305 days**	**2024/1/1**	**2028/12/29**
11	1.3.1) 多桶板小系统联调测试	1.3.1) joint commissioning test of multi barrel small system	240 days	2024/1/1	2024/12/1
12	1.3.2) 搭建桶板接收测试系统	1.3.2) build a barrel receiving test system	240 days	2024/1/1	2024/12/1
13	1.3.3) 接收、测试运往 CERN 的首批桶板	1.3.3) receive and test the first batch of barrels shipped to CERN	43 days	2025/1/1	2025/3/1
14	1.3.4) 中国生产的硅探测器模块加载到 RAL 的桶板上	1.3.4) the silicon detector module made in China is loaded on the barrel of ral	261 days	2025/1/1	2025/12/31
15	1.3.5) 完成测试后运往 CERN 安装点	1.3.5) transport to CERN installation site after testing	261 days	2026/1/1	2026/12/31
16	1.3.6) 封闭桶部探测器，联调测试	1.3.6) closed barrel detector, joint commissioning test	261 days	2027/1/1	2027/12/31
17	1.3.7) 早期运行	1.3.7) early operation	260 days	2028/1/3	2028/12/29
18	**2）时间像素探测器**	**2) Time pixel detector**	**1305 days**	**2024/1/1**	**2028/12/31**
19	**2.1）传感器**	**2.1) sensor**	**1305 days**	**2024/1/1**	**2028/12/31**
20	2.1.1）整体架构设计	2.1.1) overall architecture design	262 days	2024/1/1	2024/12/31
21	2.1.2）第一版设计	2.1.2) first edition design	261 days	2025/1/1	2025/12/31
22	2.1.3）第一版测试	2.1.3) first version test	261 days	2026/1/1	2026/12/31
23	2.1.4）第二版设计	2.1.4) second edition design	261 days	2027/1/1	2027/12/31
24	2.1.5）性能评估	2.1.5) performance evaluation	260 days	2028/1/3	2028/12/31
25	**2.2）电子学**	**2.2) Electronics**	**1305 days**	**2024/1/1**	**2028/12/31**
26	2.2.1）整体架构设计	2.2.1) overall architecture design	262 days	2024/1/1	2024/12/31
27	2.2.2）第一版原型验证电路设计	2.2.2) design of the first version prototype verification circuit	261 days	2025/1/1	2025/12/31
28	2.2.3) 第一版原型验证电路性能的仿真验证	2.2.3) simulation verification of circuit performance in the first version of prototype verification	261 days	2026/1/1	2026/12/31
29	2.2.4）第一版性能评估测试	2.2.4) first edition performance evaluation test	129 days	2027/1/1	2027/6/30
30	2.2.5) 第二版电路设计和仿真	2.2.5) circuit design and Simulation of the second edition	132 days	2027/7/1	2027/12/31
31	2.2.6）完成电子学性能评估测试	2.2.6) complete the electronic performance evaluation test	260 days	2028/1/3	2028/12/31
32	**3）项目文档**	**3) Project documentation**	**804 days**	**2025/12/2**	**2028/12/31**
33	3.1）项目中期测试报告	3.1) Interim test report of the project	22 days	2025/12/2	2025/12/31
34	3.2）项目结题报告	3.2) project conclusion report	21 days	2028/12/1	2028/12/31